

ABSTRACT

Provided is a thermally conductive film-like adhesive capable of sufficiently advancing a curing reaction under milder conditions, capable of
5 effectively suppressing residual voids between the adhesive and a wiring board in a semiconductor package to be obtained when used as a die attach film, and capable of obtaining a semiconductor package excellent in heat releasing property inside the package. In addition, provided are a semiconductor package using the thermally conductive film-like adhesive and a method of producing the
10 same.

(No Suitable Figure)